

ABSTRACT OF THE DISCLOSURE

A replaceable light emitting diode (LED) package assembly has a separate structure and manufacturing process of the LED package. The LED die and a set of fluorescent material are located on a substrate. The fluorescent material device can be arranged selectively to match a required emission color according to the characteristic of wavelength of the LED die and not only is blended precisely to provide the required color but also reduces the rate of 5 defects for the individual components of the assembly.